



Prof. Sungnam Chang

(Hanyang Univ. / PeDiSem Ltd., Korea)

- **2025. Mar. – Present: Hanyang University**
 - Research Professor (Department of Electronic Engineering)
- **2013, Nov. – 2025. Feb.: Applied Materials Korea**
 - Senior Technical Director (Process Integration TD: Beyond scaling tech trends for DRAM, NAND, Foundry, Advanced Packaging & Process Integration for based module (Integrated Material Solution))
- **2012, Nov – 2013, Nov: Samsung Electronics**
 - Principal Engineer & Director (Vertical NAND Flash & Advanced Process Integration)
- **2009, Nov- 2012, Nov: Samsung Austin Texas LLC, USA**
 - NAND Device Transfer and Production
- **1989, April – 2009, Nov: Samsung Electronics**
 - Principal Engineer & Director (SRAM/ NAND Flash & Advanced Process Integration)
- Over **35 years** of experience in **Semiconductor Process Integration**, specializing in **DRAM, NAND, Foundry and Advanced Packaging Technologies**.
- Led **key projects in DRAM/NAND/Foundry scaling, 3D IC packaging, and Cu-to-Cu hybrid bonding**.
- Holder of **18 U.S. patents, around 50 Korea patents, abroad 9 papers and Korea 2 papers**, and author of multiple **international technical papers**.

Education

- Mar.1984 – Feb.1986 Master of Science in Physics, Hanyang University, Korea B.A. in Physics, Hanyang University, Korea
- Mar.1980 – Feb.1984 B.A. in Physics, Hanyang University, Korea